

FEMTOCLOCKS™ CRYSTAL-TO-3.3V LVPECL FREQUENCY SYNTHESIZER

ICS843004-01

GENERAL DESCRIPTION



The ICS843004-01 is a 4 output LVPECL synthesizer optimized to generate Ethernet reference clock frequencies and is a member of the HiPerClocks™ family of high performance clock solutions from ICS. Using a 25MHz 18pF parallel

resonant crystal, the following frequencies can be generated based on the settings of 2 frequency select pins (F_SEL[1:0]): 156.25MHz, 125MHz, 62.5MHz. The ICS843004-01 uses ICS' 3rd generation low phase noise VCO technology and can achieve 1ps or lower typical rms phase jitter, easily meeting Ethernet jitter requirements. The ICS843004-01 is packaged in a small 24-pin TSSOP package.

FEATURES

- Four 3.3V LVPECL outputs
- Selectable crystal oscillator interface or LVCMOS/LVTTL single-ended input
- Supports the following output frequencies: 156.25MHz, 125MHz and 62.5MHz
- VCO range: 560MHz 680MHz
- RMS phase jitter @ 156.25MHz, using a 25MHz crystal (1.875MHz - 20MHz): 0.57ps (typical)
- RMS phase noise at 156.25MHz (typical)

Phase noise:

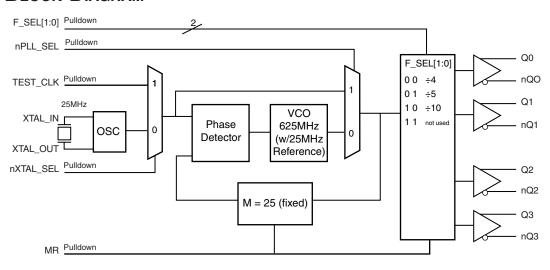
Offset	Noise Power
100Hz	95.5 dBc/Hz
1kHz	118 dBc/Hz
10kHz	126 dBc/Hz
100kHz	126.6 dBc/Hz

- Full 3.3V supply mode
- -30°C to 85°C ambient operating temperature
- Available in both standard and lead-free RoHS compliant packages

FREQUENCY SELECT FUNCTION TABLE

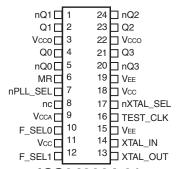
	Output Frequency				
F_SEL1	F_SEL0	M Divider Value	N Divider Value	M/N Divider Value	(25MHz Ref.)
0	0	25	4	6.25	156.25
0	1	25	5	5	125
1	0	25	10	2.5	62.5
1	1	25	not used		not used

BLOCK DIAGRAM



1

PIN ASSIGNMENT



ICS843004-01 24-Lead TSSOP

4.40mm x 7.8mm x 0.92mm package body

G Package Top View

TABLE 1. PIN DESCRIPTIONS

Number	Name	Ty	/ре	Description
1, 2	nQ1, Q1	Output		Differential output pair. LVPECL interface levels.
3, 22	V _{cco}	Power		Output supply pins.
4, 5	Q0, nQ0	Ouput		Differential output pair. LVPECL interface levels.
6	MR	Input	Pulldown	Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the true outputs Qx to go low and the inverted outputs nQx to go high. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS/LVTTL interface levels.
7	nPLL_SEL	Input	Pulldown	Selects between the PLL and TEST_CLK as input to the dividers. When LOW, selects PLL (PLL Enable). When HIGH, deselects the reference clock (PLL Bypass). LVCMOS/LVTTL interface levels.
8	nc	Unused		No connect.
9	V_{CCA}	Power		Analog supply pin.
10, 12	F_SEL0, F_SEL1	Input	Pulldown	Frequency select pins. LVCMOS/LVTTL interface levels.
11, 18	V_{cc}	Power		Core supply pin.
13, 14	XTAL_OUT, XTAL_IN	Input		Parallel resonant crystal interface. XTAL_OUT is the output, XTAL_IN is the input.
15, 19	V_{EE}	Power		Negative supply pins.
16	TEST_CLK	Input	Pulldown	LVCMOS/LVTTL clock input.
17	nXTAL_SEL	Input	Pulldown	Selects between crystal or TEST_CLK inputs as the the PLL Reference source. Selects XTAL inputs when LOW. Selects TEST_CLK when HIGH. LVCMOS/LVTTL interface levels.
20, 21	nQ3, Q3	Output		Differential output pair. LVPECL interface levels.
23, 24	Q2, nQ2	Output		Differential output pair. LVPECL interface levels.

NOTE: Pulldown refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC} 4.6V

Inputs, V_1 -0.5V to V_{cc} + 0.5V

Outputs, I_o

Continuous Current 50mA Surge Current 100mA

Package Thermal Impedance, θ_{JA} 70°C/W (0 mps) Storage Temperature, T_{STG} -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 3A. Power Supply DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = -30°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{cc}	Core Supply Voltage		3.135	3.3	3.465	V
V _{CCA}	Analog Supply Voltage		3.135	3.3	3.465	V
V _{cco}	Output Supply Voltage		3.135	3.3	3.465	V
I _{EE}	Power Supply Current				135	mA
I _{CCA}	Analog Supply Current	Included in I _{EE}			15	mA

Table 3B. LVCMOS / LVTTL DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = -30°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V _{IH}	Input High Vol	tage		2		V _{cc} + 0.3	V
V _{IL}	Input	nPLL_SEL, nXTAL_SEL, F_SEL0, F_SEL1, MR		-0.3		0.8	V
- IL	Low Voltage	TEST_CLK		-0.3		1.3	V
I _{IH}	Input High Current	TEST_CLK, MR, nPLL_SEL, nXTAL_SEL, F_SEL0, F_SEL1	$V_{CC} = V_{IN} = 3.465V$			150	μΑ
I _{IL}	Input Low Current	TEST_CLK, MR, nPLL_SEL, nXTAL_SEL, F_SEL0, F_SEL1	V _{CC} = 3.465V, V _{IN} = 0V	-5			μΑ

Table 3C. LVPECL DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = -30°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{OH}	Output High Voltage; NOTE 1		V _{cco} - 1.4		V _{cco} - 0.9	V
V _{OL}	Output Low Voltage; NOTE 1		V _{cco} - 2.0		V _{cco} - 1.7	V
V _{SWING}	Peak-to-Peak Output Voltage Swing		0.6	·	1.0	V

NOTE 1: Outputs terminated with 50 $\!\Omega$ to ${\rm V_{cco}}$ - 2V.

TABLE 4. CRYSTAL CHARACTERISTICS

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation		Fundamental			
Frequency			25		MHz
Equivalent Series Resistance (ESR)				50	Ω
Shunt Capacitance				7	pF

NOTE: Characterized using an 18pF parallel resonant crystal.

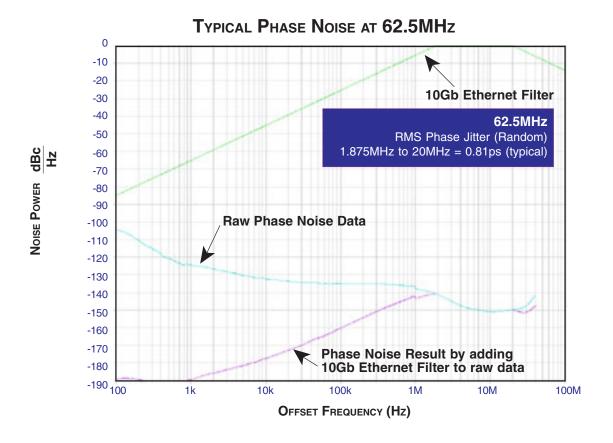
Table 5. AC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = -30°C to 85°C

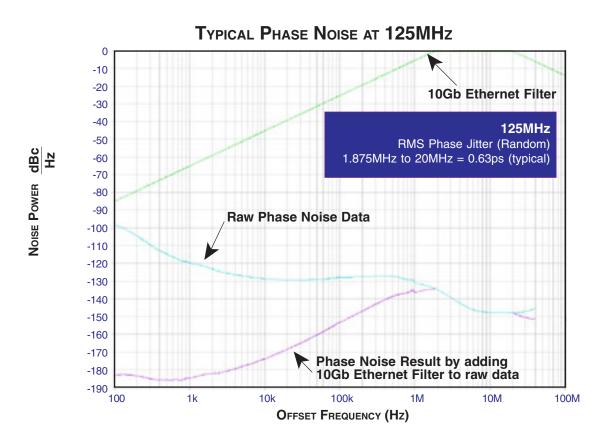
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
		F_SEL[1:0] = 00	140		170	MHz
f _{out}	Output Frequency	F_SEL[1:0] = 01	112		136	MHz
		F_SEL[1:0] =10	56		68	MHz
tsk(o)	Output Skew; NOTE 1, 2				30	ps
		156.25MHz (1.875MHz - 20MHz)		0.57		ps
<i>t</i> jit(Ø)	RMS Phase Jitter; NOTE 3	125MHz (1.875MHz - 20MHz)		0.63		ps
		62.5MHz (1.875MHz - 20MHz)		0.81		ps
t _R / t _F	Output Rise/Fall Time	20% to 80%	300		600	ps
odc	Output Duty Cycle		49		51	%

NOTE 1: Defined as skew between outputs at the same supply voltages and with equal load conditions.

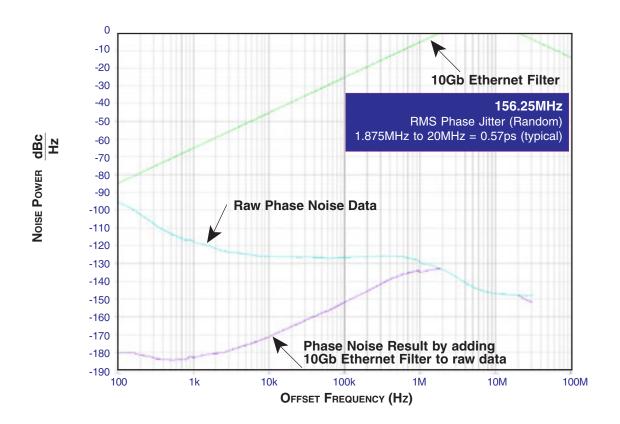
Measured at $\rm V_{\rm cco}/2.$ NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 3: Phase jitter is dependent on the input source used.

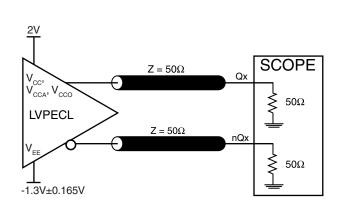


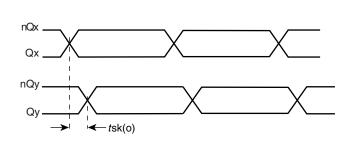


Typical Phase Noise at 156.25MHz

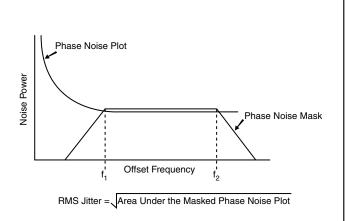


PARAMETER MEASUREMENT INFORMATION

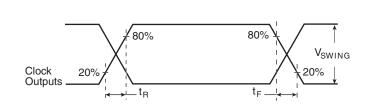




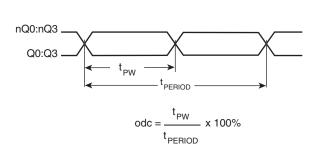
3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT



OUTPUT SKEW



RMS PHASE JITTER



OUTPUT RISE/FALL TIME

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

APPLICATION INFORMATION

Power Supply Filtering Techniques

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS843004-01 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. $V_{\rm CC},\,V_{\rm CCA},\,$ and $V_{\rm CCO}$ should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. Figure 1 illustrates how a 10Ω resistor along with a $10\mu F$ and a $.01\mu F$ bypass capacitor should be connected to each $V_{\rm CCA}$.

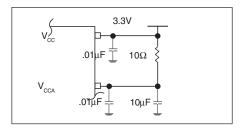


FIGURE 1. POWER SUPPLY FILTERING

RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

INPUTS:

CRYSTAL INPUT:

For applications not requiring the use of the crystal oscillator input, both XTAL_IN and XTAL_OUT can be left floating. Though not required, but for additional protection, a 1kW resistor can be tied from XTAL_IN to ground.

TEST_CLK INPUT:

For applications not requiring the use of the test clock, it can be left floating. Though not required, but for additional protection, a $1k\Omega$ resistor can be tied from the TEST_CLK to ground.

LVCMOS CONTROL PINS:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A $1k\Omega$ resistor can be used.

OUTPUTS:

LVPECL OUTPUT

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

CRYSTAL INPUT INTERFACE

The ICS843004-01 has been characterized with 18pF parallel resonant crystals. The capacitor values shown in *Figure 2* below

were determined using a 25MHz, 18pF parallel resonant crystal and were chosen to minimize the ppm error.

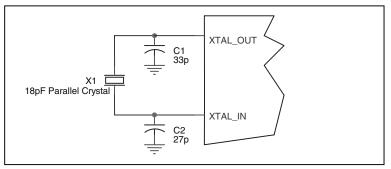


Figure 2. Crystal Input Interface

LVCMOS TO XTAL INTERFACE

The XTAL_IN input can accept a single-ended LVCMOS signal through an AC coupling capacitor. A general interface diagram is shown in *Figure X*. The XTAL_OUT pin can be left floating. The input edge rate can be as slow as 10ns. For LVCMOS inputs, it is recommended that the amplitude be reduced from full swing to half swing in order to prevent signal interference with the power rail and to reduce noise. This configuration requires that the output

impedance of the driver (Ro) plus the series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First, R1 and R2 in parallel should equal the transmission line impedance. For most 50Ω applications, R1 and R2 can be 100Ω . This can also be accomplished by removing R1 and making R2 50Ω .

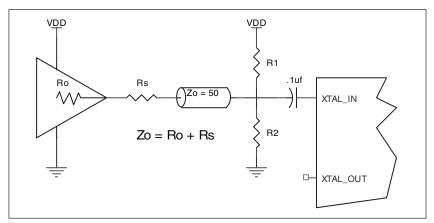


FIGURE 3. GENERAL DIAGRAM FOR LVCMOS DRIVER TO XTAL INPUT INTERFACE

TERMINATION FOR 3.3V LVPECL OUTPUT

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are

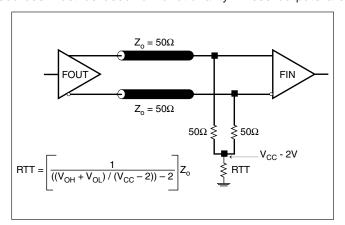


FIGURE 4A. LVPECL OUTPUT TERMINATION

designed to drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. Figures 4A and 4B show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

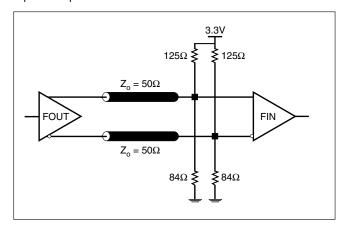


FIGURE 4B. LVPECL OUTPUT TERMINATION

LAYOUT GUIDELINE

Figure 5 shows a schematic example of the ICS843004-01. An example of LVEPCL termination is shown in this schematic. Additional LVPECL termination approaches are shown in the LVPECL Termination Application Note. In this example, an 18pF

parallel resonant 25MHz crystal is used. The C1=27pF and C2=33pF are recommended for frequency accuracy. For different board layout, the C1 and C2 may be slightly adjusted for optimizing frequency accuracy.

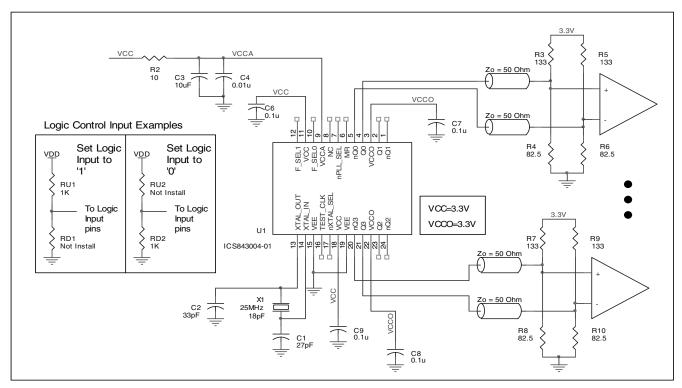


FIGURE 5. ICS843004-01 SCHEMATIC EXAMPLE

POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS843004-01. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS843004-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{cc} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = V_{CC.MAX} * I_{EE.MAX} = 3.465V * 135mA = 467.8mW
- Power (outputs)_{MAX} = 30mW/Loaded Output pair
 If all outputs are loaded, the total power is 4 * 30mW = 120mW

Total Power (3.465V, with all outputs switching) = 467.8mW + 120mW = 587.8mW

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for Tj is as follows: Tj = θ_{JA} * Pd_total + T_A

Tj = Junction Temperature

 $\theta_{_{JA}}$ = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T₄ = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance $\theta_{\text{\tiny JA}}$ must be used. Assuming a moderate air flow of 1 meter per second and a multi-layer board, the appropriate value is 65°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is: 85°C + 0.588W * 65°C/W = 123.2°C. This is below the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 6. Thermal Resistance $\theta_{_{JA}}$ for 24-pin TSSOP, Forced Convection

θ_{JA} by Velocity (Meters per Second) 0 1 2.5 Multi-Layer PCB, JEDEC Standard Test Boards 70°C/W 65°C/W 62°C/W

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load. LVPECL output driver circuit and termination are shown in *Figure 6*.

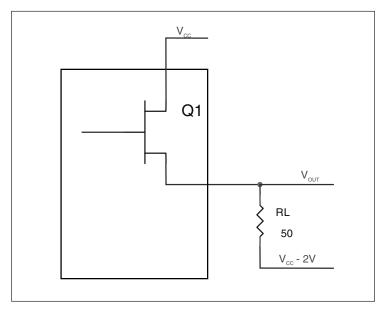


FIGURE 6. LVPECL DRIVER CIRCUIT AND TERMINATION

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{∞} - 2V.

• For logic high,
$$V_{OUT} = V_{OH_MAX} = V_{CC_MAX} - 0.9V$$

$$(V_{CCO_MAX} - V_{OH_MAX}) = 0.9V$$

• For logic low,
$$V_{OUT} = V_{OL_MAX} = V_{CC_MAX} - 1.7V$$

$$(V_{CCO_MAX} - V_{OL_MAX}) = 1.7V$$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$\begin{split} &\text{Pd_H} = [(\text{V}_{\text{OH_MAX}} - (\text{V}_{\text{CC_MAX}} - 2\text{V}))/\text{R}_{\text{L}}] * (\text{V}_{\text{CC_MAX}} - \text{V}_{\text{OH_MAX}}) = [(2\text{V} - (\text{V}_{\text{CC_MAX}} - \text{V}_{\text{OH_MAX}}))/\text{R}_{\text{L}}] * (\text{V}_{\text{CC_MAX}} - \text{V}_{\text{OH_MAX}}) = [(2\text{V} - 0.9\text{V})/50\Omega] * 0.9\text{V} = \textbf{19.8mW} \\ &\text{Pd_L} = [(\text{V}_{\text{OL_MAX}} - (\text{V}_{\text{CC_MAX}} - 2\text{V}))/\text{R}_{\text{L}}] * (\text{V}_{\text{CC_MAX}} - \text{V}_{\text{OL_MAX}}) = [(2\text{V} - (\text{V}_{\text{CC_MAX}} - \text{V}_{\text{OL_MAX}}))/\text{R}_{\text{L}}] * (\text{V}_{\text{CC_MAX}} - \text{V}_{\text{OL_MAX}}) = [(2\text{V} - 1.7\text{V})/50\Omega] * 1.7\text{V} = \textbf{10.2mW} \end{split}$$

Total Power Dissipation per output pair = Pd_H + Pd_L = 30mW

TRANSISTOR COUNT

RELIABILITY INFORMATION

Table 7. $\theta_{_{JA}} \text{vs. Air Flow Table for 24 Lead TSSOP}$

 θ_{M} by Velocity (Meters per Second)

13

2.5 70°C/W 65°C/W 62°C/W

Multi-Layer PCB, JEDEC Standard Test Boards

The transistor count for ICS843004-01 is: 3183

PACKAGE OUTLINE - G SUFFIX FOR 24 LEAD TSSOP

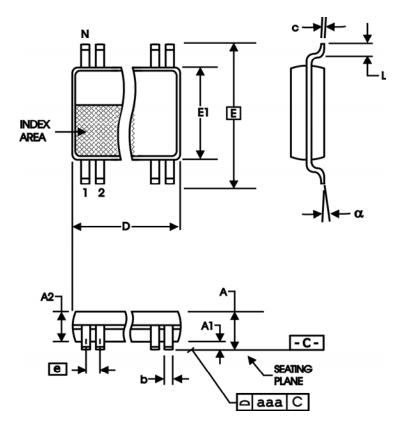


TABLE 8. PACKAGE DIMENSIONS

CYMPOL	Millin	neters
SYMBOL	Minimum	Maximum
N	2	4
A		1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
С	0.09	0.20
D	7.70	7.90
E	6.40 E	BASIC
E1	4.30	4.50
е	0.65 E	BASIC
L	0.45	0.75
α	0°	8°
aaa		0.10

Reference Document: JEDEC Publication 95, MO-153

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TABLE 9. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS843004AG-01	ICS843004A01	24 Lead TSSOP	tube	-30°C to 85°C
ICS843004AG-01T	ICS843004A01	24 Lead TSSOP	2500 tape & reel	-30°C to 85°C
ICS843004AG-01LF	ICS43004A01L	24 Lead "Lead-Free" TSSOP	tube	-30°C to 85°C
ICS843004AG-01LFT	ICS43004A01L	24 Lead "Lead-Free" TSSOP	2500 tape & reel	-30°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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	REVISION HISTORY SHEET						
Rev	Table	Page	Description of Change	Date			
В	T5	4	AC Characteristics Table - deleted Propagation Delay row.	5/6/05			
		1	Features Section - added lead-free bullet.				
В		9	Added - LVCMOS to XTAL Interface and Recommendations for Unused Input and Output Pins sections.	6/30/06			
	Т9	15	Ordering Information Table - added lead-free part number, marking and note.				

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